

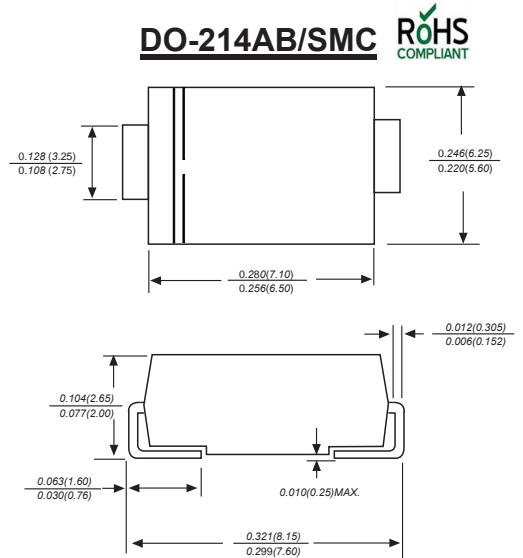
SURFACE MOUNT SCHOTTKY BARRIER RECTIFIER

Features

- ◆ The plastic package carries Underwriters Laboratory Flammability Classification 94V-0
- ◆ For surface mounted applications
- ◆ Metal silicon junction, majority carrier conduction
- ◆ Low power loss, high efficiency
- ◆ Built-in strain relief, ideal for automated placement
- ◆ High forward surge current capability
- ◆ High temperature soldering guaranteed:
250 °C/10 seconds at terminals

Mechanical Data

Case: JEDEC DO-214AB/SMC molded plastic body
 Terminals: Solderable per MIL-STD-750, Method 2026
 Polarity: Color band denotes cathode end Mounting
 Position: Any
 Weight : 0.0077 ounce, 0.22grams



Dimensions in inches and (millimeters)

Maximum Ratings And Electrical Characteristics

Ratings at 25 °C ambient temperature unless otherwise specified. Single phase, half wave, 60Hz resistive or inductive load, for capacitive load, derate by 20 %

Parameter	Symbols	SK104C SK1045C	SK106C	SK1010C	SK1020C	Units
Maximum Repetitive Peak Reverse Voltage	V_{RRM}	45	60	100	200	V
Maximum RMS voltage	V_{RMS}	32	42	70	140	V
Maximum DC Blocking Voltage	V_{DC}	45	60	100	200	V
Maximum Average Forward Rectified Current	$I_{F(AV)}$	10.0				A
Peak Forward Surge Current, 8.3ms Single Half Sine-wave Superimposed on Rated Load (JEDEC method)	I_{FSM}	150				A
Max Instantaneous Forward Voltage @10.0 A	V_F	0.55	0.75	0.95	0.95	V
Maximum DC Reverse Current at $T_a = 25^{\circ}C$ Rated DC Reverse Voltage $T_a = 100^{\circ}C$	I_R	0.5 50				mA
Typical thermal resistance	$R_{\theta JA}$	25				$^{\circ}C/W$
Operating Junction Temperature Range	T_j	-55 ~ +150				$^{\circ}C$
Storage Temperature Range	T_{stg}	-55 ~ +150				$^{\circ}C$

Typical Characteristics

Fig.1 Forward Current Derating Curve

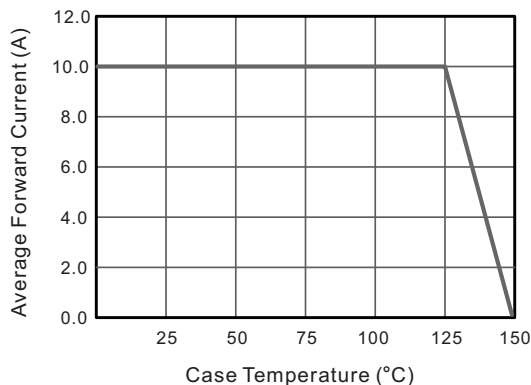


Fig.2 Typical Reverse Characteristics

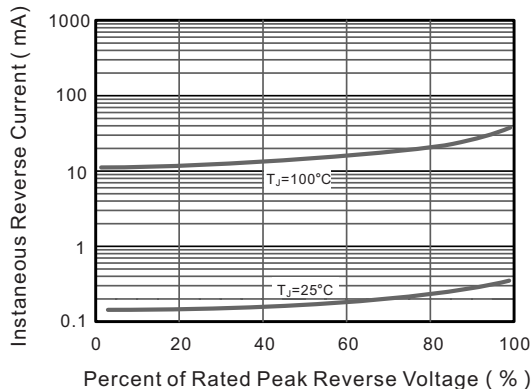


Fig.3 Typical Forward Characteristic

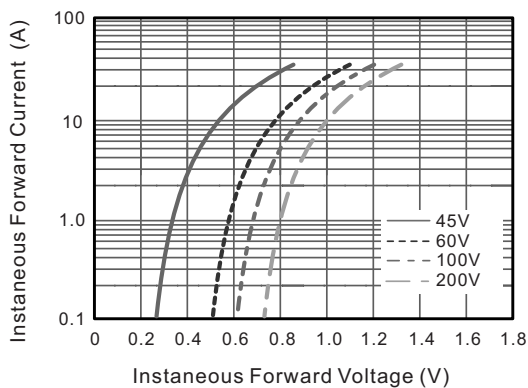


Fig.4 Typical Junction Capacitance

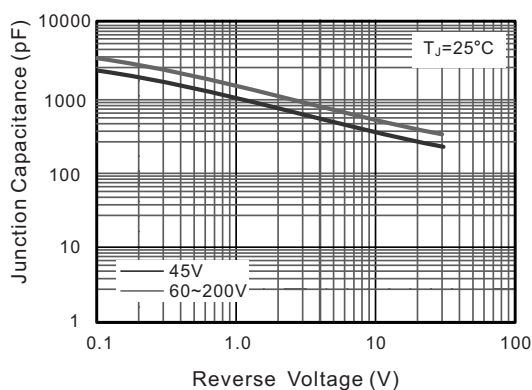


Fig.5 Maximum Non-Repetitive Peak Forward Surge Current

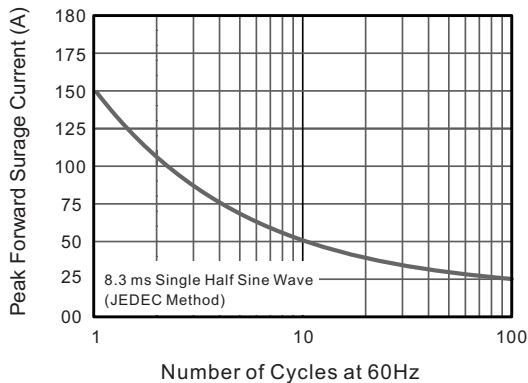
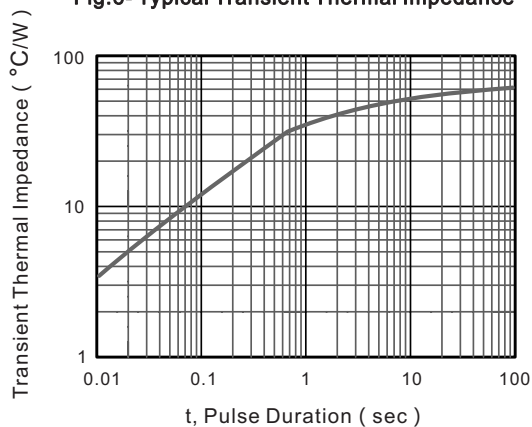
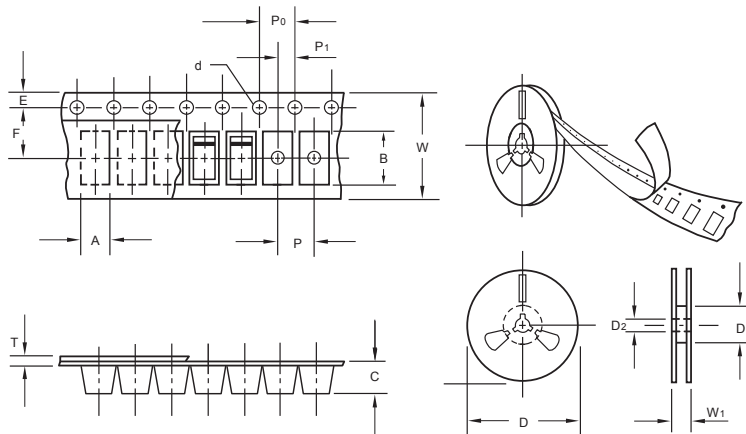


Fig.6- Typical Transient Thermal Impedance



The curve above is for reference only.

Packing information



unit:mm

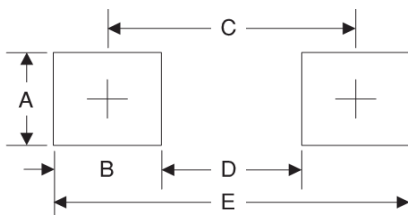
Item	Symbol	Tolerance	SMC
Carrier width	A	0.1	6.15
Carrier length	B	0.1	8.41
Carrier depth	C	0.1	2.42
Sprocket hole	d	0.05	1.50
13" Reel outside diameter	D	2.0	330.00
13" Reel inner diameter	D ₁	min	50.00
Feed hole diameter	D ₂	0.5	13.00
Sprocket hole position	E	0.1	1.75
Punch hole position	F	0.1	7.50
Punch hole pitch	P	0.1	8.00
Sprocket hole pitch	P ₀	0.1	4.00
Embossment center	P ₁	0.1	2.00
Overall tape thickness	T	0.1	0.25
Tape width	W	0.3	16.00
Reel width	W ₁	1.0	16.50

Note: Devices are packed in accordance with EIA standard RS-481-A and specifications listed above.

Reel packing

PACKAGE	REEL SIZE	REEL (pcs)	COMPONENT SPACING (mm)	BOX (pcs)	INNER BOX (mm)	REEL DIA, (mm)	CARTON SIZE (mm)	CARTON (pcs)	APPROX. GROSS WEIGHT (kg)
SMC	13"	3,000	4.0	6000	190*190*41	330	365*365*340	42000	14.0

Suggested Pad Layout



Symbol	Unit (mm)	Unit (inch)
A	4.3	0.170
B	4.1	0.160
C	7.9	0.311
D	3.8	0.150
E	12	0.472

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